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TIDA-050007

TIDA-050007 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		TIDA-050007	Any	Printed Circuit Board	
C1, C2, C3, C8, C11, C14, C15	7	10uF	GRM188R61A106ME69D	MuRata	CAP, CERM, 10 uF, 10 V, +/- 20%, X5R, 0603	0603
C4, C18	2	1000pF	GRM1885C1E102JA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0603	0603
C6, C10, C12	3	0.1uF	06033D104KAT2A	AVX	CAP, CERM, 0.1 uF, 25 V, +/- 10%, X5R, 0603	0603
C7, C9	2	10uF	C1005X5R0J106M050BC	TDK	CAP, CERM, 10 uF, 6.3 V, +/- 20%, X5R, 0402	0402
C13	1	0.1uF	GRM155R61E104KA87D	MuRata	CAP, CERM, 0.1 uF, 25 V, +/- 10%, X5R, 0402	0402
D1, D2	2	Red	BR1112H-TR	Stanley Electric Co., LTD	LED, Red, SMD	2x1.25mm
J1, J4, J5, J6	4		5-146278-4	TE Connectivity	Header, 100mil, 4x1, Tin, TH	Header, 4x1, 100mil, TH
J2	1		SBH11-PBPC-D07-ST-BK	Sullins Connector Solutions	Header (shrouded), 100 mil, 7x2, Gold, TH	7x2 Shrouded Header
J3	1		473460001	Molex	Connector, Receptacle, Micro-USB Type B, R/A, Bottom Mount SMT	7.5x2.45x5mm
J7, J8, J10	3		TSW-102-17-G-S	Samtec	Header, 2.54mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
L1	1	2.2uH	DFE252012F-2R2M=P2	MuRata Toko	Inductor, Shielded, Powdered Iron, 2.2 uH, 2.3 A, 0.082 ohm, SMD	2.5x1.2x2mm
LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650 x 0.200 inch
R1, R2	2	549	RT0603DRE07549RL	Yageo America	RES, 549, 0.5%, 0.1 W, 0603	0603
R3	1	1.40k	RT0603BRD071K4L	Yageo America	RES, 1.40 k, 0.1%, 0.1 W, 0603	0603
R4	1	1.47k	RT0603DRE071K47L	Yageo America	RES, 1.47 k, 0.5%, 0.1 W, 0603	0603
R5	1	56.2k	RC0603FR-0756K2L	Yageo America	RES, 56.2 k, 1%, 0.1 W, 0603	0603
R6	1	10.0k	RC0603FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R7, R22	2	200k	RG1608P-204-B-T5	Susumu Co Ltd	RES, 200 k, 0.1%, 0.1 W, 0603	0603
R8, R9, R12, R13	4	2.00	RC0603FR-072RL	Yageo	RES, 2.00, 1%, 0.1 W, 0603	0603
R10	1	255k	RT0603DRE07255KL	Yageo America	RES, 255 k, 0.5%, 0.1 W, 0603	0603
R11	1	1.00Meg	MCT06030C1004FP500	Vishay/Beyschlag	RES, 1.00 M, 1%, 0.125 W, 0603	0603
R14	1	180k	RC0402FR-07180KL	Yageo America	RES, 180 k, 1%, 0.063 W, 0402	0402
R15	1	6.81k	RC0402FR-076K81L	Yageo America	RES, 6.81 k, 1%, 0.063 W, 0402	0402
R16	1	1.0k	RC0603JR-071KL	Yageo	RES, 1.0 k, 5%, 0.1 W, 0603	0603
R17	1	10.0k	RC0402FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R18	1	348k	RT0603DRE07348KL	Yageo America	RES, 348 k, 0.5%, 0.1 W, 0603	0603
R19	1	576k	RC0603FR-07576KL	Yageo America	RES, 576 k, 1%, 0.1 W, 0603	0603
R26	1	47.5k	RT0603BRD0747K5L	Yageo America	RES, 47.5 k, 0.1%, 0.1 W, 0603	0603
R27, R28, R29	3	0	RMCF0603ZT0R00	Stackpole Electronics Inc	RES, 0, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
U1	1		BQ24073RGTR	Texas Instruments	USB Friendly 0.5 A Li+ Charger with Dynamic Power Management, 6.6 V OVP, 4.3 V, -40 to 85 degC, 16-pin QFN (RGT), Green (RoHS & no Sb/Br)	RGT0016C
U2	1		TPS7A0525PDBV	Texas Instruments	1uA IQ, 200 mA, Ultralow IQ Low-Dropout Regulator, DBV0005A (SOT-5)	DBV0005A
U3	1		TPS61099YFFR	Texas Instruments	Synchronous Boost Converter with 800 nA Ultra-Low Quiescent Current, YFF0006AFAD (DSBGA-6)	YFF0006AFAD
U4	1		BQ25100AYFPR	Texas Instruments	250-mA Single Cell Li-Ion Battery Charger, 1mA termination, 75nA Battery leakage, YFP0006AFAV (DSBGA-6)	YFP0006AFAV
U5	1		MSP430FR2100IPW16R	Texas Instruments	16 MHz Ultra-Low-Power Microcontroller With 1 KB FRAM, 0.5 KB SRAM, 12 IO, 8 ch ADC10, PW0016A (TSSOP-16)	PW0016A

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